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2N4264
2N4265

CASE 29-02, STYLE 1
TO-92 (TO-226AA)

GENERAL PURPOSE TRANSISTOR

NPN SILICON

THERMAL CHARACTERISTICS

Characteristic	Symbol	2N4264	2N4265	Unit
Collector-Emitter Voltage	V_{CEO}	15	12	Vdc
Collector-Base Voltage	V_{CBO}	30		Vdc
Emitter-Base Voltage	V_{EBO}	6.0		Vdc
Collector Current — Continuous	I_C	200		mAdc
Total Device Dissipation @ $T_A = 25°C$ Derate above 25°C	P_D	625 5.0		mW mW/°C
Total Device Dissipation @ $T_C = 25°C$ Derate above 25°C	P_D	1.5 12		Watts mW/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}	−55 to +150		°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	83.3	°C/W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	200	°C/W

ELECTRICAL CHARACTERISTICS ($T_A = 25°C$ unless otherwise noted.)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Breakdown Voltage ($I_C = 1.0$ mAdc, $I_E = 0$)	 2N4264 2N4265	$V_{(BR)CEO}$	 15 12	 — —	Vdc
Collector-Base Breakdown Voltage ($I_C = 10$ μAdc, $I_E = 0$)		$V_{(BR)CBO}$	20	—	Vdc
Emitter-Base Breakdown Voltage ($I_E = 10$ μAdc, $I_C = 0$)		$V_{(BR)EBO}$	6.0	—	Vdc
Base Cutoff Current ($V_{CE} = 12$ Vdc, $V_{EB(off)} = 0.25$ Vdc) ($V_{CE} = 12$ Vdc, $V_{EB(off)} = 0.25$ Vdc, $T_A = 100°C$)		I_{BEV}	 — —	 0.1 10	μAdc
Collector Cutoff Current ($V_{CE} = 12$ Vdc, $V_{EB(off)} = 0.25$ Vdc)		I_{CEX}	—	100	nAdc
ON CHARACTERISTICS					
DC Current Gain ($I_C = 1.0$ mAdc, $V_{CE} = 1.0$ Vdc)	 2N4264 2N4265	h_{FE}	 25 30	 — —	—
($I_C = 10$ mAdc, $V_{CE} = 1.0$ Vdc)	2N4264 2N4265		40 100	160 400	
($I_C = 10$ mAdc, $V_{CE} = 1.0$ Vdc, $T_A = -55°C$)	2N4264 2N4265		20 45	— —	
($I_C = 30$ mAdc, $V_{CE} = 1.0$ Vdc)	2N4264 2N4265		40 90	— —	
($I_C = 100$ mAdc, $V_{CE} = 1.0$ Vdc)(1)	2N4264 2N4265		30 55	— —	
($I_C = 200$ mAdc, $V_{CE} = 1.0$ Vdc)(1)	2N4264 2N4265		20 35	— —	
Collector-Emitter Saturation Voltage ($I_C = 10$ mAdc, $I_B = 1.0$ mAdc) ($I_C = 100$ mAdc, $I_B = 10$ mAdc)(1)		$V_{CE(sat)}$	 — —	 0.22 0.35	Vdc
Base-Emitter Saturation Voltage ($I_C = 10$ mAdc, $I_B = 1.0$ mAdc) ($I_C = 100$ mAdc, $I_B = 10$ mAdc)(1)		$V_{BE(sat)}$	 0.65 0.75	 0.80 0.95	Vdc

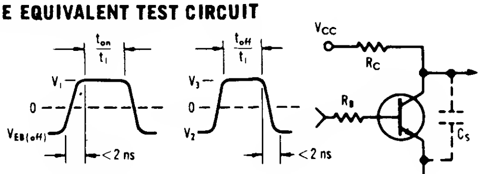
ELECTRICAL CHARACTERISTICS (continued) (T_A = 25°C unless otherwise noted.)

Characteristic		Symbol	Min	Max	Unit
SMALL-SIGNAL CHARACTERISTICS					
Current-Gain — Bandwidth Product (I_C = 10 mAdc, V_{CE} = 10 Vdc, f = 100 MHz)		f_T	350	—	MHz
Input Capacitance (V_{BE} = 0.5 Vdc, I_C = 0, f = 1.0 MHz)		C_{ibo}	—	8.0	pF
Collector-Base Capacitance (V_{CB} = 5.0 Vdc, I_E = 0, f = 1.0 MHz)		C_{cb}	—	4.0	pF
SWITCHING CHARACTERISTICS					
Delay Time	(V_{CC} = 10 Vdc, $V_{EB(off)}$ = 2.0 Vdc, I_C = 100 mAdc, I_{B1} = 10 mAdc) (Fig. 1, Test Condition C)	t_d	—	8.0	ns
Rise Time		t_r	—	15	ns
Storage Time	V_{CC} = 10 Vdc, (I_C = 10 mAdc, for t_s) (I_C = 100 mA for t_f) I_{B1} = I_{B2} = 10 mAdc) (Fig. 1, Test Condition C)	t_s	—	20	ns
Fall Time		t_f	—	15	ns
Turn-On Time	(V_{CC} = 3.0 Vdc, $V_{EB(off)}$ = 1.5 Vdc, I_C = 10 mAdc, I_{B1} = 3.0 mAdc) (Fig. 1, Test Condition A)	t_{on}	—	25	ns
Turn-Off Time	(V_{CC} = 3.0 Vdc, I_C = 10 mAdc, I_{B1} = 3.0 mAdc, I_{B2} = 1.5 mAdc) (Fig. 1, Test Condition A)	t_{off}	—	35	ns
Storage Time	(V_{CC} = 10 Vdc, I_C = 10 mA I_{B1} = I_{B2} = 10 mAdc) (Fig. 1, Test Condition A)	t_s	—	20	ns
Total Control Charge	(V_{CC} = 3.0 Vdc, I_C = 10 mAdc, I_B = mAdc) (Fig. 1, Test Condition B)	Q_T	—	80	pC

(1) Pulse Test: Pulse Width = 300 μs, Duty Cycle = 2.0%.

FIGURE 1 — SWITCHING TIME EQUIVALENT TEST CIRCUIT

TEST CONDITION	I_C	V_{CC}	R_B	R_C	$C_{S(max)}$	$V_{EB(off)}$	V_1	V_2	V_3
	mA	V	Ω	Ω	pF	V	V	V	V
A	10	3	3300	270	4	−1.5	10.55	−4.15	10.70
B	10	10	560	960	4	—	—	−4.65	6.55
C	100	10	560	96	12	−2.0	6.35	−4.65	6.55



PULSE WIDTH (t_1) = 300 ns DUTY CYCLE = 2%

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CURRENT GAIN CHARACTERISTICS

FIGURE 2 — MINIMUM CURRENT GAIN

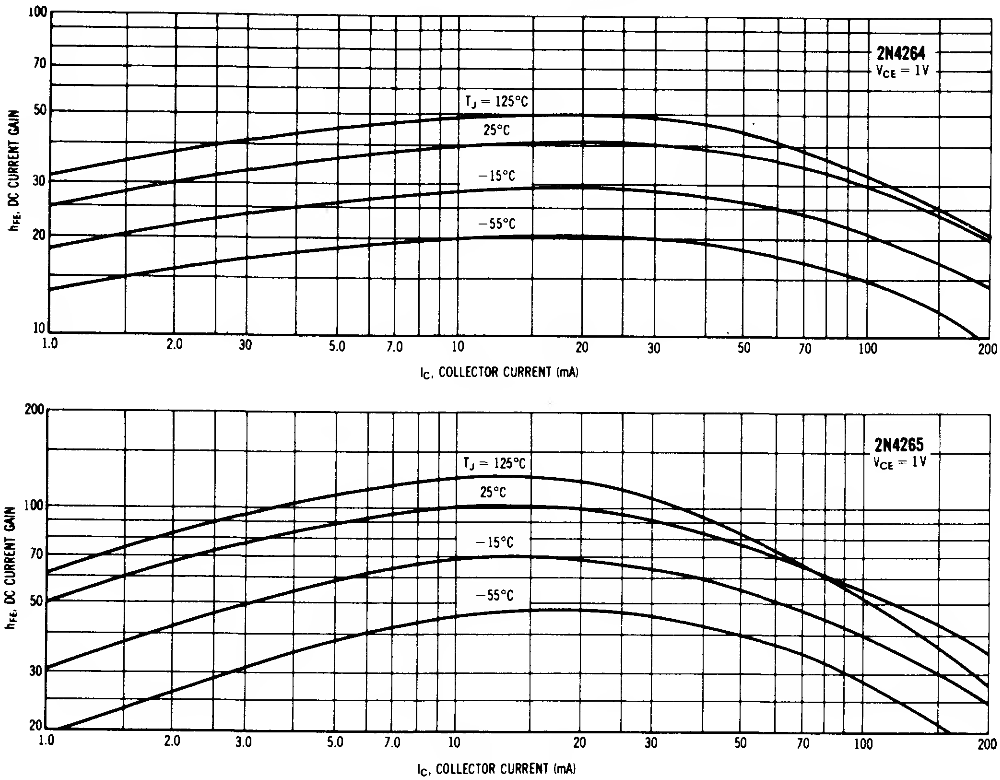


FIGURE 3 — Q_T TEST CIRCUIT

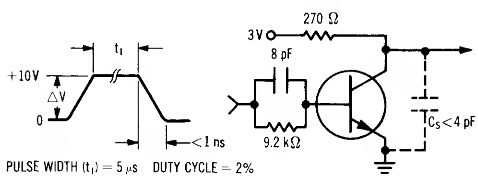
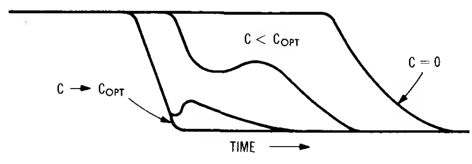


FIGURE 4 — TURN-OFF WAVEFORM



NOTE 1

When a transistor is held in a conductive state by a base current, I_B, a charge, Q_S, is developed or "stored" in the transistor. Q_S may be written: $Q_S = Q_1 + Q_V + Q_X$.

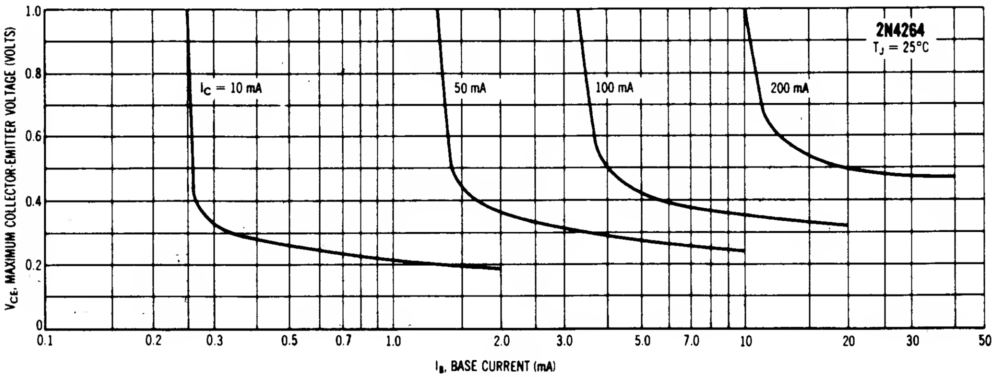
Q_1 is the charge required to develop the required collector current. This charge is primarily a function of alpha cutoff frequency. Q_V is the charge required to charge the collector-base feedback capacity. Q_X is excess charge resulting from overdrive, i.e., operation in saturation.

The charge required to turn a transistor "on" to the edge of saturation is the sum of Q_1 and Q_V which is defined as the active region charge, Q_A. $Q_A = I_{B1}t_r$ when the transistor is driven by a constant current step (I_{B1}) and $I_{B1} << \frac{I_C}{h_{FE}}$.

If I_B were suddenly removed, the transistor would continue to conduct until Q_S is removed from the active regions through an external path or through internal recombination. Since the internal recombination time is long compared to the ultimate capability of a transistor, a charge, Q_T, of opposite polarity, equal in magnitude, can be stored on an external capacitor, C, to neutralize the internal charge and considerably reduce the turn-off time of the transistor. Figure 3 shows the test circuit and Figure 4 the turn-off waveform. Given Q_T from Figure 13, the external C for worst-case turn-off in any circuit is: $C = Q_T/\Delta V$, where ΔV is defined in Figure 3.

"ON" CONDITION CHARACTERISTICS

FIGURE 5 — COLLECTOR SATURATION REGION



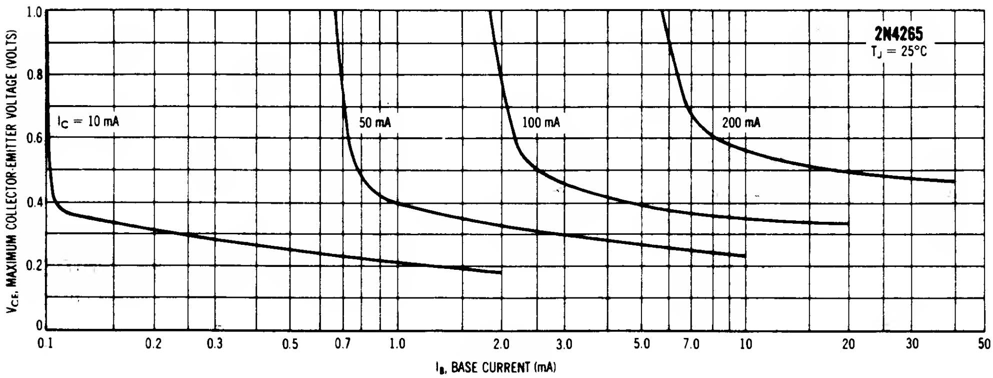


FIGURE 6 — SATURATION VOLTAGE LIMITS

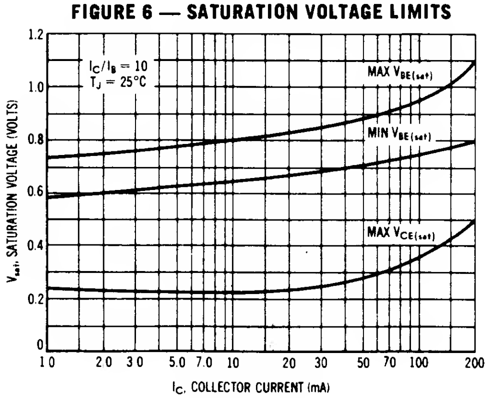
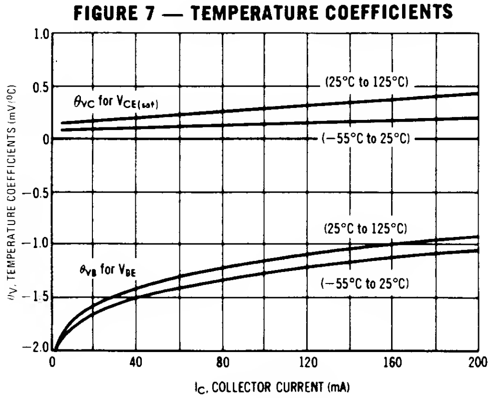


FIGURE 7 — TEMPERATURE COEFFICIENTS



DYNAMIC CHARACTERISTICS

FIGURE 8 — DELAY TIME

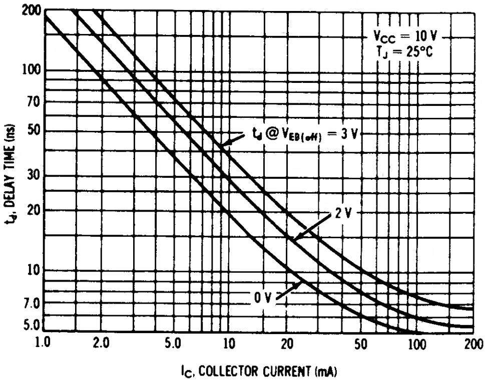


FIGURE 9 — RISE TIME

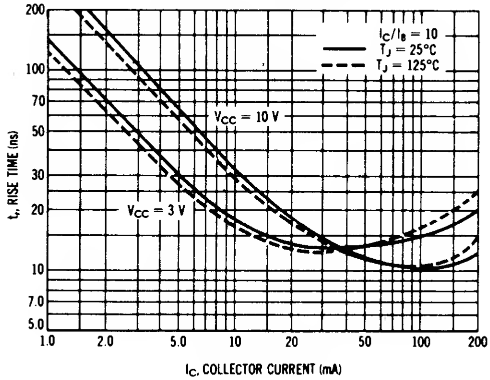


FIGURE 10 — STORAGE TIME

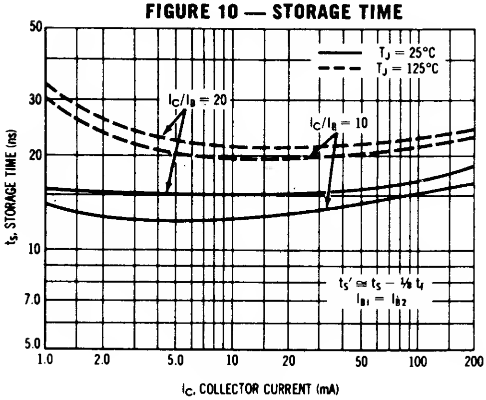


FIGURE 11 — FALL TIME

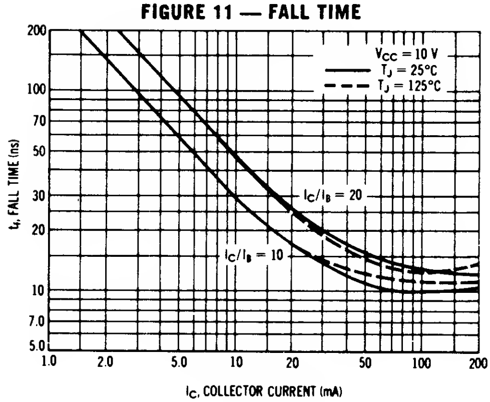


FIGURE 12 — JUNCTION CAPACITANCE

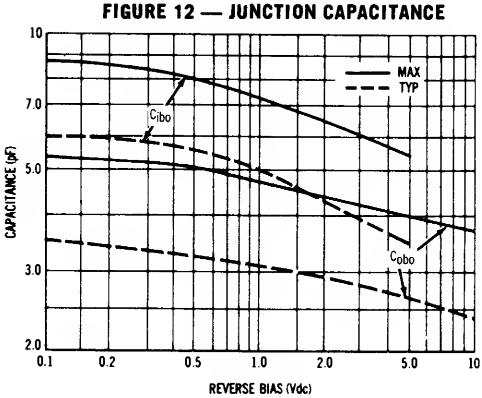


FIGURE 13 — MAXIMUM CHARGE DATA